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FDS8449

40V N-Channel PowerTrench® MOSFET

General Description

These N-Channel MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize on-state resistance and yet maintain superior switching performance.

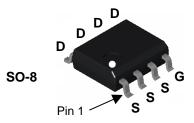
Application

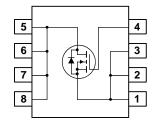
- Inverter
- Power Supplies

Features

- 7.6 A, 40V $R_{DS(on)} = 29m\Omega$ @ $V_{GS} = 10V$ $R_{DS(on)} = 36m\Omega$ @ $V_{GS} = 4.5V$
- High power handling capability in a widely used surface mount package
- RoHS compliant







Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		40	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Drain Current - Continuous	(Note 1a)	7.6	A
	- Pulsed		50	
P _D	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1b)	125	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	25	

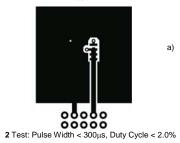
Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS8449	FDS8449	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-So	ource Avalanche Ratings (Note	e 3)			I	1
E _{AS}	Drain-Source Avalanche Energy	$V_{DD} = 40 \text{ V}, I_D = 7.3 \text{ A}, L = 1 \text{ mH}$			27	mJ
I _{AS}	Drain-Source Avalanche Current			7.3		Α
Off Char	acteristics				•	•
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$	40			V
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		34		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 32 \text{ V}, \qquad V_{GS} = 0 \text{ V}$			1	μΑ
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1	1.9	3	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		-5		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	$\begin{split} V_{GS} &= 10 \text{ V}, & I_D = 7.6 \text{ A} \\ V_{GS} &= 4.5 \text{ V}, & I_D = 6.8 \text{ A} \\ V_{GS} &= 10 \text{ V}, I_D = 7.6 \text{ A}, T_J = 125 ^{\circ}\text{C} \end{split}$		21 26 29	29 36 43	mΩ
g FS	Forward Transconductance	$V_{DS} = 10 \text{ V}, \qquad I_{D} = 7.6 \text{ A}$		21		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V},$		760		pF
Coss	Output Capacitance	f = 1.0 MHz		100		pF
C _{rss}	Reverse Transfer Capacitance			60		pF
R _G	Gate Resistance	f = 1.0 MHz		1.2		Ω
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 20 \text{ V}, \qquad I_D = 1 \text{ A},$		9	18	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		5	10	ns
t _{d(off)}	Turn-Off Delay Time			23	17	ns
t _f	Turn-Off Fall Time			3	6	ns
Qg	Total Gate Charge	$V_{DS} = 20 \text{ V}, \qquad I_{D} = 7.6 \text{ A},$		7.7	11	nC
Q_{gs}	Gate-Source Charge	$V_{GS} = 5 V$		2.4		nC
Q_{gd}	Gate-Drain Charge			2.8		nC
Drain-So	ource Diode Characteristics					
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{S} = 2.1 \text{ A (Note 2)}$		0.76	1.2	V
t _{rr}	Diode Reverse Recovery Time	$I_{\rm F} = 7.6 \text{ A}, \qquad d_{\rm iF}/d_{\rm f} = 100 \text{ A/}\mu\text{s}$		17		nS
Q _{rr}	Diode Reverse Recovery Charge	$\eta_{iF} = 1.0 \text{ A}, \qquad \alpha_{iF}/\alpha_t = 100 \text{ A/}\mu\text{S}$		7		nC

Notes:

1. R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



50°C/W when mounted on a 1in² pad of 2 oz copper



- b) 125°C/W when mounted on a minimum pad.
- Scale 1:1 on letter size paper

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- 3. BV(avalanche) Single-Pulse rating is guaranteed if device is operated within the UIS SOA boundary of the device.

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Typical Characteristics

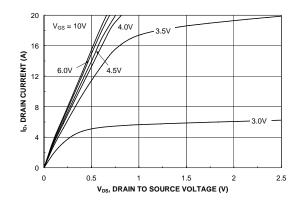


Figure 1. On-Region Characteristics.

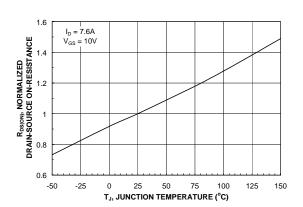


Figure 3. On-Resistance Variation with Temperature.

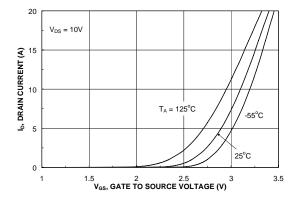


Figure 5. Transfer Characteristics.

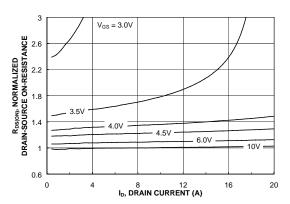


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

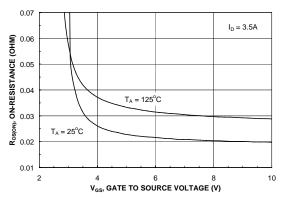


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

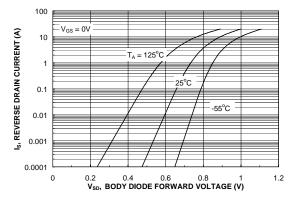


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

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Typical Characteristics

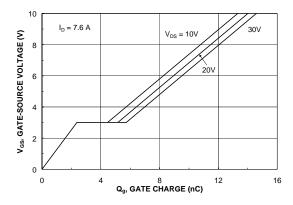
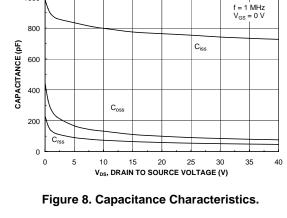


Figure 7. Gate Charge Characteristics.



1000

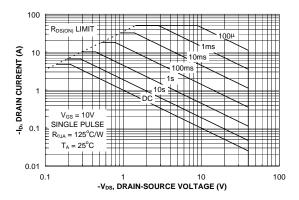


Figure 9. Maximum Safe Operating Area.

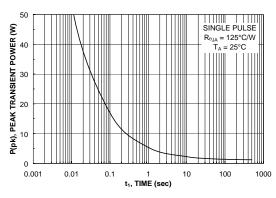


Figure 10. Single Pulse Maximum Power Dissipation.

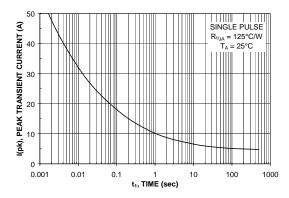


Figure 11. Single Pulse Maximum Peak Current.

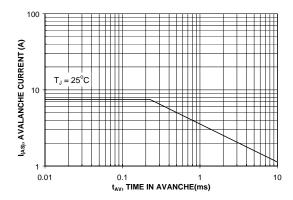


Figure 12. Unclamped Inductive Switching Capability.

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Typical Characteristics

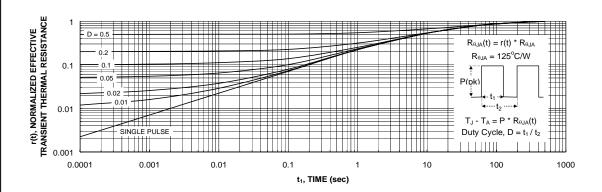


Figure 25. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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